

QT-Brightek Chip LED Series

SMD Side View 0802 LED

Part No.: QBLP612-YG

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Introduction

Feature:

- Water clear lens
- Package in tape and reel
- Side View Ultra bright 0802 LED package
- GaP technology for YG

Description:

These ultra bright 0802 LEDs have a height profile of 0.6mm. With higher packing density and smaller footprint, these LEDs are ideal for smaller equipment and miniature application.

Application:

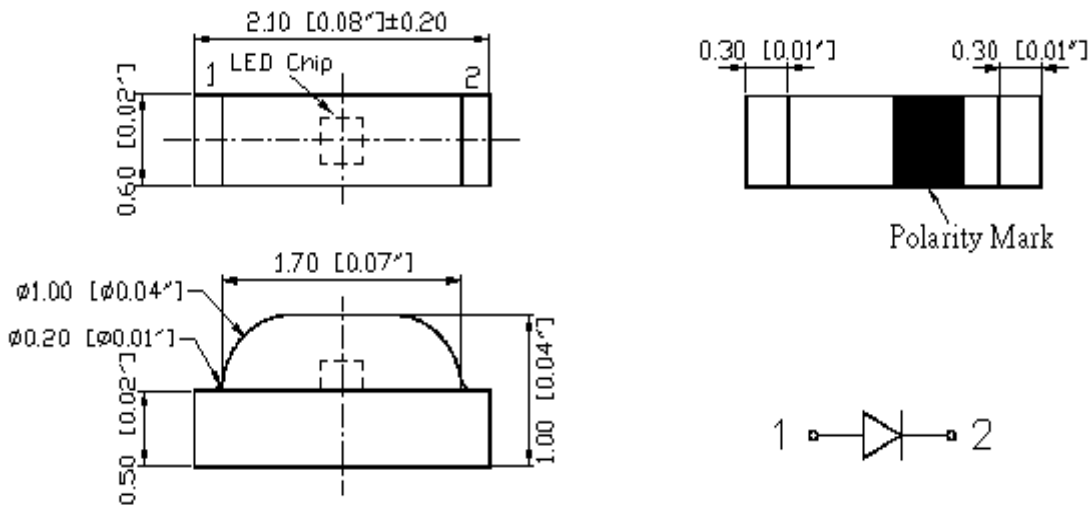
- Status indication
- Back lighting application
- General Use

Certification & Compliance:

- TS16949
- ISO9001
- RoHS Compliant



Dimension:



Units: mm / tolerance = +/-0.1mm

Electrical / Optical Characteristic (Ta=25 °C)

Product	Color	I _F (mA)	V _F (V)		λ _D (nm)			I _V (mcd)	
			Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.
QBLP612-YG	Yellow Green	20	2.0	2.5	565	570	576	5.0	15

Absolute Maximum Rating

Material	P _d (mW)	I _F (mA)	I _{FP} (mA)*	V _R (V)	T _{OP} (°C)	T _{ST} (°C)	T _{SOL} (°C)**
GaP	75	30	125	5	-40 ~ +80	-40 ~ +85	260

*Duty 1/8 @ 1kHz

**IR Reflow for no more than 10 sec @ 260 °C

Forward Voltage V_F @ I_F=20mA

Bin	Min.	Max.	Unit
<input type="checkbox"/>	1.7	2.5	V

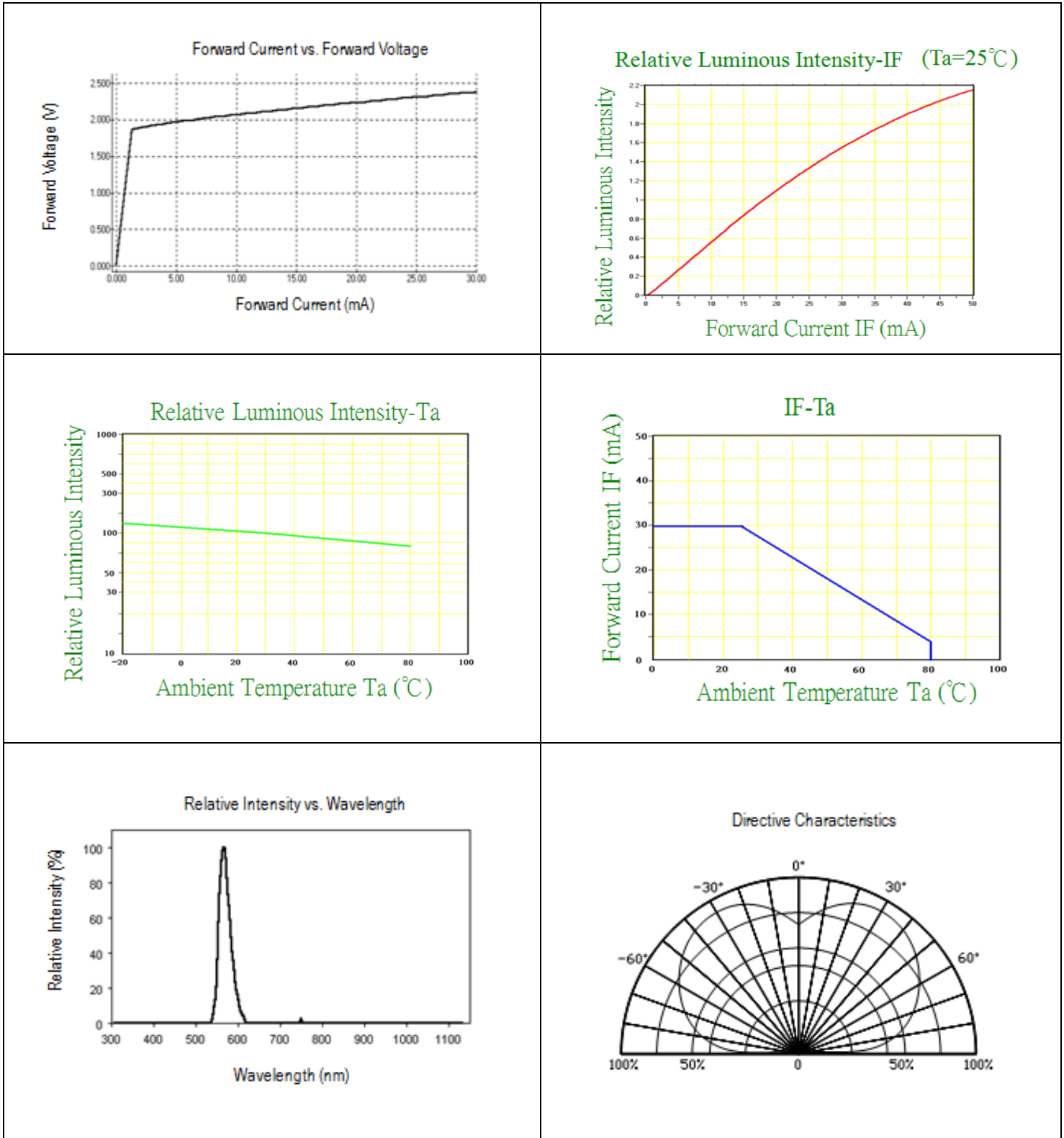
Luminous Intensity I_V @ I_F=20mA

Bin	Min.	Max.	Unit
8	5.0	8.0	mcd
9	8.0	12.5	
A	12.5	16	
B	16	20	
C	20	25	

Dominant Wavelength λ_D @ I_F=20mA

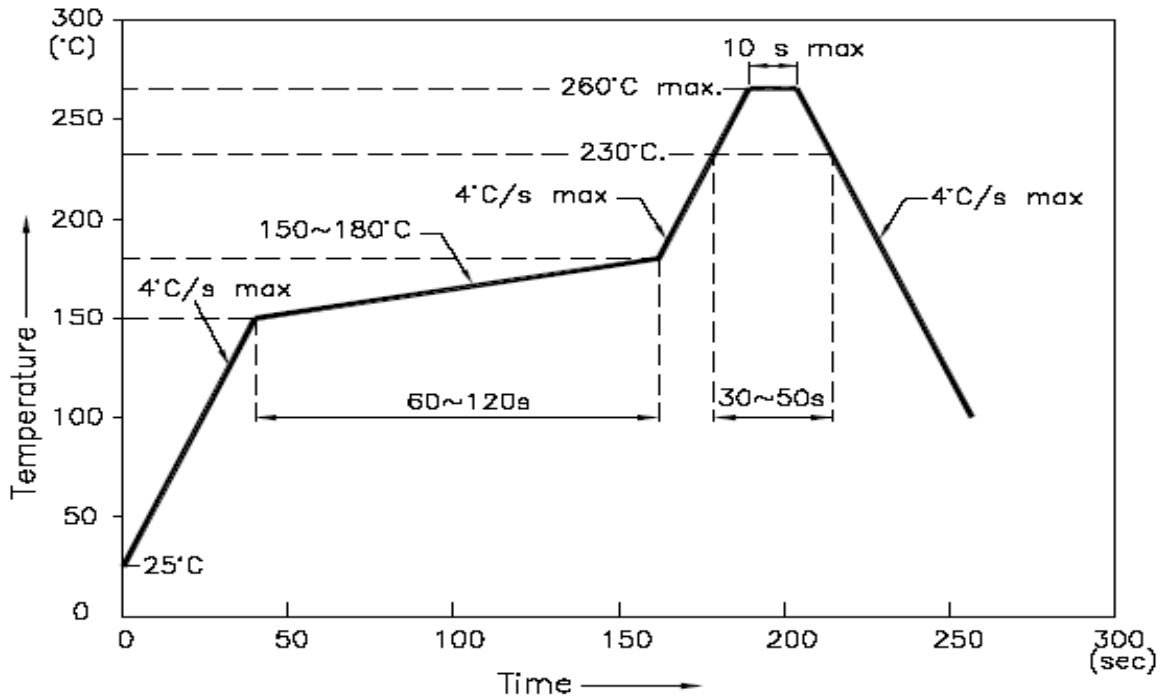
Bin	Min.	Max.	Unit
h	565	568	nm
i	568	572	
j	572	576	

Characteristic Curves

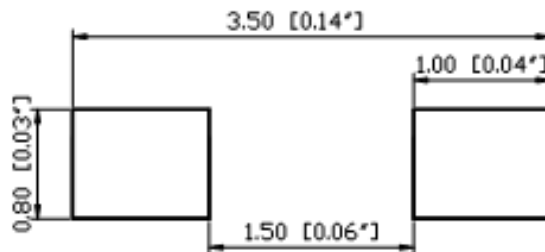


Solder Profile & Footprint

- Recommended tin solder specifications: melting temperature in the range of 178~192 °C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):



Recommended Pad Layout

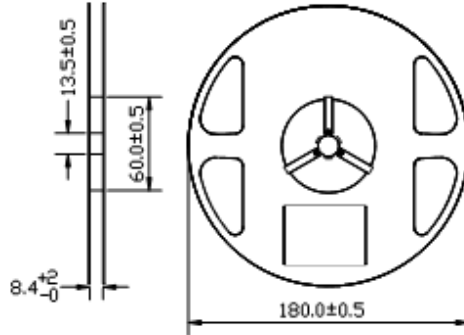


Units: mm

Tolerance: ± 0.1mm

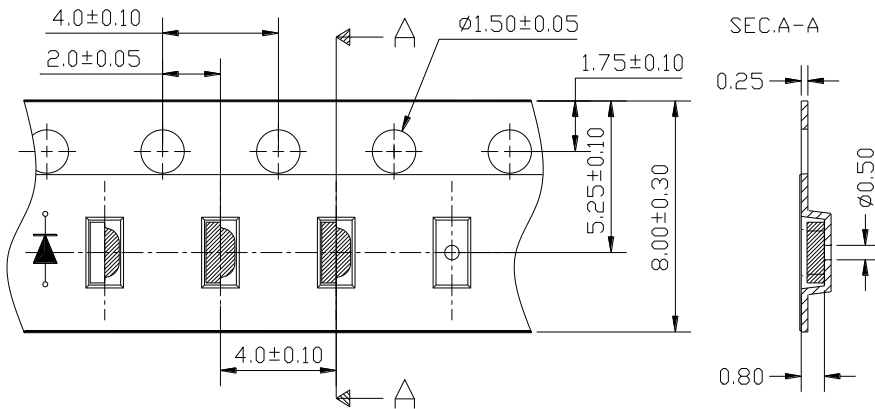
Packing

Reel Dimension:



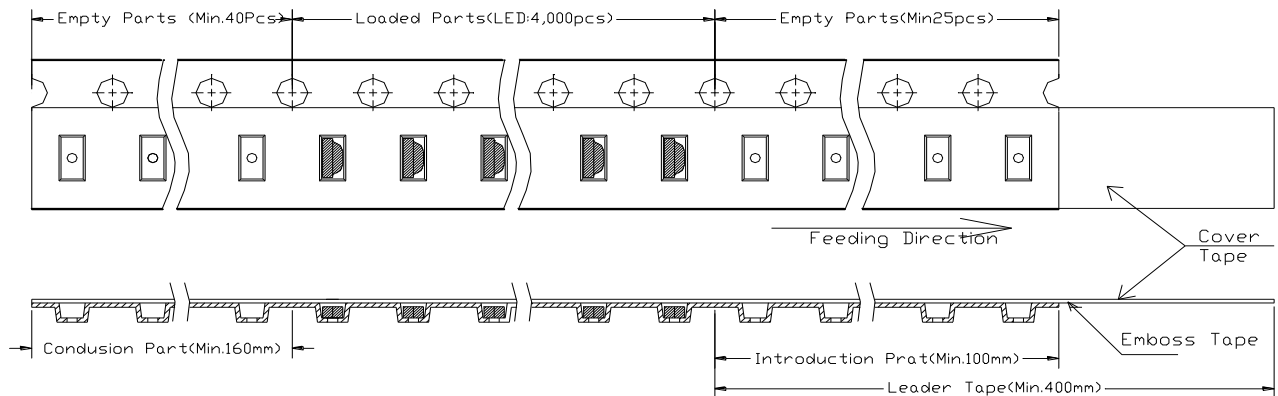
Unit: mm

Tape Dimension:



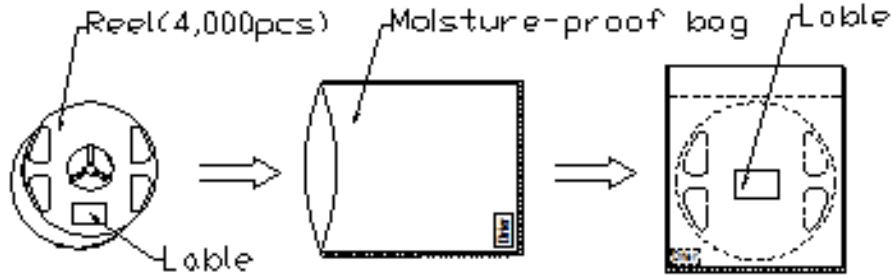
Unit: mm

Arrangement of Tape:



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Packaging Specifications:



Labeling



Part No: _____
Customer P/N: _____
Item: _____
Q'ty: _____
Vf: _____
Iv: _____
WI: _____
Date: _____

Made in China

Ordering Information

Part #	Orderable Part #	Spec Range	Quantity per reel
QBLP612-YG	QBLP612-YG	Iv=15mcd typ. @ I _F =20mA, λ _D : 565nm ~ 576nm	4,000 units

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Revision History

Description:	Revision #	Revision Date
New Release of QBLP612-YG	V1.0	09/16/2014

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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